

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 10/004,172  
Filing Date .... October 9, 2001  
Inventor .... Warren M. Farnworth et al.  
Assignee .... Micron Technology, Inc.  
Group Art Unit .... 3729  
Examiner .... D. Tugbang  
Attorney's Docket No. .... MI22-1839  
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding  
Frames

**EXAMINER INTERVIEW SUMMARY OF FEBRUARY 6, 2003**

To: Assistant Commissioner for Patents  
Washington, D.C. 20231

From: D. Brent Kenady  
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Group 3700**

Applicant's representative held an interview with Examiner Tugbang on February 6, 2003. Applicant's representative would like to thank Examiner Tugbang for his time and attention to this matter.

The Examiner requested an election from numerous alleged species of the pending claims. No agreement was reached, and therefore no election was made.

Respectfully submitted,

Dated: 2-11-03

By: 

D. Brent Kenady  
Reg. No. 40,045

Practitioner's Docket No. MI22-1839

PATENT

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Farnworth et al, Warren M.

Application No.: 10/004,172

Group No.: 3729

Filed: 10/09/01

Examiner: D. Tugbang

For: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding Frames

Assistant Commissioner for Patents  
Washington, D.C. 20231

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## CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being facsimile transmitted to the Patent and Trademark Office at (703) 872-9301 on the date shown below:

Examiner Interview Summary of February 6, 2003

2/11/03  
Date

Robin Saldivia

  
Signature

TOTAL PAGES - 2

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